

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition
1	BRS	L1	155	(rins\$3 or wash\$3) same (nonaqueous) same (solvent or liquid or ammine or dimethylsulfoxie or DMSO or propanalamide or analine or dimethylaniline or alcohol or acetone) same (semiconductor or wafer or substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2005/09/01 16:37		
2	BRS	L2	24	1 and (cmp or ((chemical\$2 mechanical\$2) adj (polish\$3 or planariz\$5)) or polish\$3 or planariz\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2005/09/01 16:39		
3	BRS	L3	23680	(rins\$3 or wash\$3) same ((cmp or ((chemical\$2 mechanical\$2) adj (polish\$3 or planariz\$5)) or polish\$3 or planariz\$5))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2005/09/01 16:40		
4	BRS	L4	1	1 same (cmp or ((chemical\$2 mechanical\$2) adj (polish\$3 or planariz\$5)) or polish\$3 or planariz\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2005/09/01 16:39		
5	BRS	L5	5947	((rins\$3 or wash\$3) same (wafer or substrate or semiconductor)) same ((cmp or ((chemical\$2 mechanical\$2) adj (polish\$3 or planariz\$5)) or polish\$3 or planariz\$5))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2005/09/01 16:43		
6	BRS	L6	1113	((rins\$3 or wash\$3) same (wafer or substrate or semiconductor)) same ((cmp or ((chemical\$2 mechanical\$2) adj (polish\$3 or planariz\$5)) or polish\$3 or planariz\$5))	EPO; JPO; DERWENT; IBM_TDB	2005/09/01 16:44		
7	BRS	L7	1109	6 and @pd<="200010830"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2005/09/01 16:44		

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition
8	BRS	L8	1113	((rins\$3 or wash\$3) same (wafer or substrate or semiconductor)) same ((cmp or ((chemical\$2 mechanical\$2) adj (polish\$3 or planariz\$5)) or polish\$3 or planariz\$5))	EPO; JPO; DERWENT; IBM_TDB	2005/09/01 18:01		
9	BRS	L9	1109	8 and @pd<="200010830"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2005/09/01 16:45		
10	BRS	L10	1109	8 and @pd<="200010830"	EPO; JPO; DERWENT; IBM_TDB	2005/09/01 16:46		
11	BRS	L11	252	((rins\$3 or wash\$3) adj3 (wafer or substrate or semiconductor)) same ((cmp or ((chemical\$2 mechanical\$2) adj (polish\$3 or planariz\$5)) or polish\$3 or planariz\$5))	EPO; JPO; DERWENT; IBM_TDB	2005/09/01 17:00		
12	BRS	L12	251	11 and @pd<="200010830"	EPO; JPO; DERWENT; IBM_TDB	2005/09/01 18:00		
13	BRS	L13	9	((nonaqueous or alcohol or acetone or DMSO or "dimethyl sulfoxide" or ammine or amine or propanalamide or dimethylaniline) same ((rins\$3 or wash\$3) adj3 (wafer or substrate or semiconductor)) same ((cmp or ((chemical\$2 mechanical\$2) adj (polish\$3 or planariz\$5)) or polish\$3 or planariz\$5)))	EPO; JPO; DERWENT; IBM_TDB	2005/09/01 17:59		
14	BRS	L14	1882	((nonaqueous or alcohol or acetone or DMSO or "dimethyl sulfoxide" or ammine or amine or propanalamide or dimethylaniline) same ((cmp or ((chemical\$2 mechanical\$2) adj (polish\$3 or planariz\$5)) or polish\$3 or planariz\$5)))	EPO; JPO; DERWENT; IBM_TDB	2005/09/01 19:28		
15	BRS	L15	1786	14 and @pd<="200010830"	EPO; JPO; DERWENT; IBM_TDB	2005/09/01 18:01		
16	BRS	L16	394	14 same (wafer or substrate or semiconductor)	EPO; JPO; DERWENT; IBM_TDB	2005/09/01 18:02		

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition
17	BRS	L17	393	16 and @pd<="200010830"	EPO; JPO; DERWENT; IBM_TDB	2005/09/01 18:02		
18	BRS	L18	105	14 same (wafer or substrate or semiconductor) same (abrasive or slurry)	EPO; JPO; DERWENT; IBM_TDB	2005/09/01 18:02		
19	BRS	L19	105	18 and @pd<="200010830"	EPO; JPO; DERWENT; IBM_TDB	2005/09/01 18:47		
20	BRS	L20	60	18 and @pd<="20010830"	EPO; JPO; DERWENT; IBM_TDB	2005/09/01 19:28		
21	BRS	L21	48	((nonaqueous or alcohol or acetone or DMSO or "dimethyl sulfoxide" or ammine or amine or propanalamide or dimethylalanine) same ((cmp or ((chemical\$2 mechanical\$2) adj (polish\$3 or planariz\$5)) or polish\$3 or planariz\$5))) and rins\$3	EPO; JPO; DERWENT; IBM_TDB	2005/09/01 19:28		
22	BRS	L22	43	21 and @pd<="20010830"	EPO; JPO; DERWENT; IBM_TDB	2005/09/01 19:40		
23	BRS	L23	122	MAY-CHARLES-E.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2005/09/01 19:41		